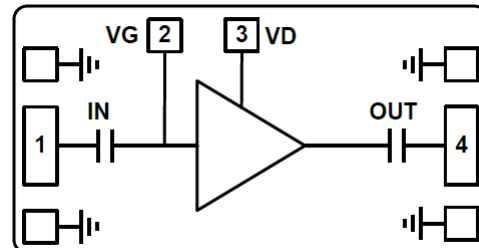


### Features

- Two operating mode: high power consumption and low power consumption
- Frequency: 18-40GHz
- Noise Figure: 2.3dB@27mA, 2.2dB@16mA
- Gain: 15dB@27mA, 13dB@16mA
- P1dB: 12dBm@27mA, 8dBm@16mA
- Power Supply: +5V@27mA, VG is floating
- +5V@16mA, VG connected to GND
- Input/Output: 50Ω
- Die Size: 1.5 x 0.8 x 0.1 mm

### Functional Block Diagram



### Typical Applications

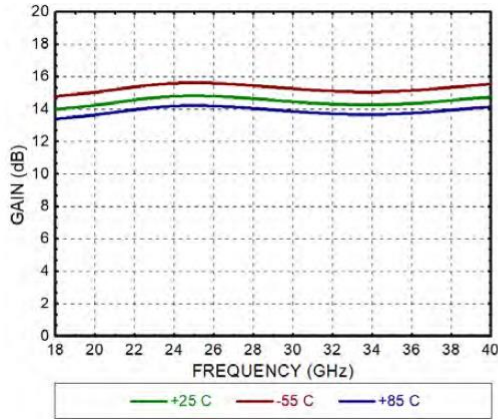
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

### Electrical Specifications

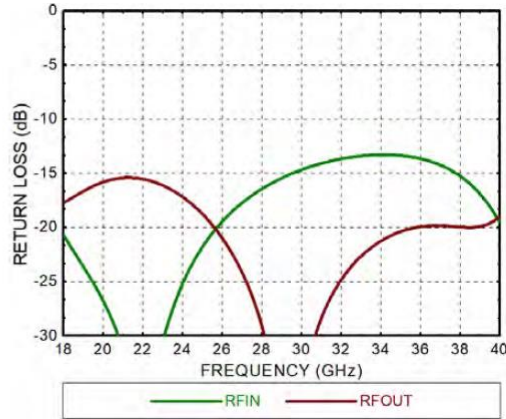
TA = +25°C, VDD=+5V

Parameters	VG is floating			VG connected to GND			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency	18-40			18-40			GHz
Gain		15			13		dB
Gain Flatness		±0.4			±0.3		dB
Input Return Loss		15			13		dB
Output Return Loss		15			15		dB
Output 1dB Compression (P1dB)		12			8		dBm
Psat		14			10		dBm
Output IP3		22			18		dBm
Noise Figure		2.3			2.2		dB
Operating current	18	27	40	10	16	25	mA

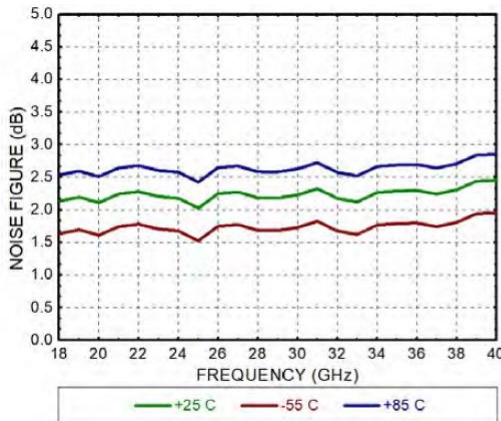
**Gain (VG is floating)**



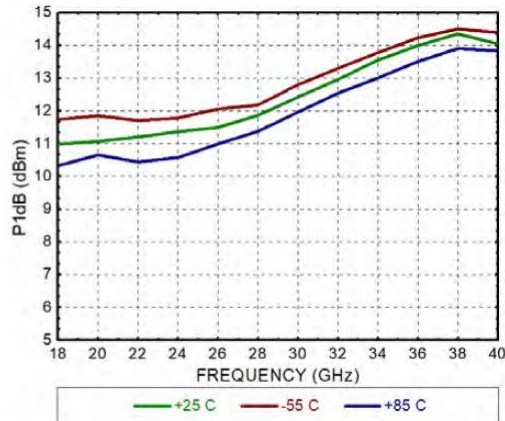
**Return Loss (VG is floating)**



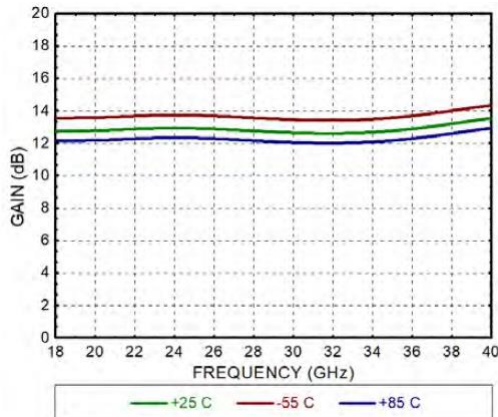
**Noise Figure (VG is floating)**



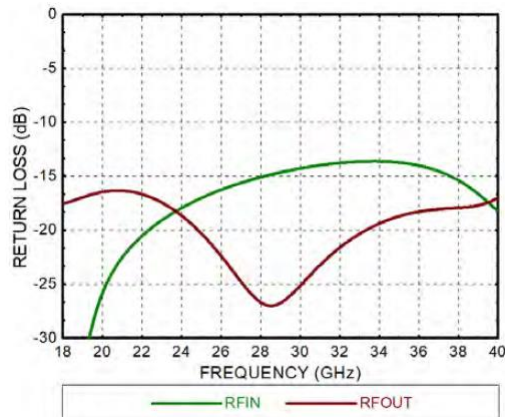
**P1dB (VG is floating)**

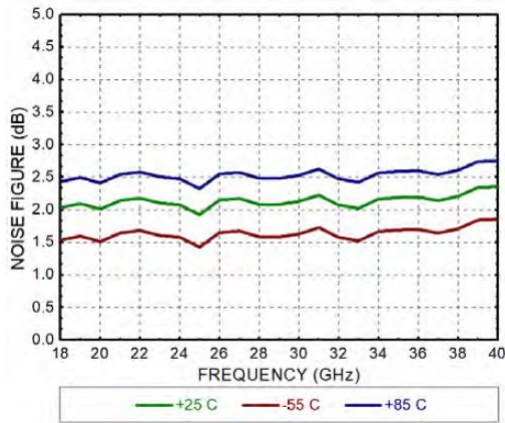
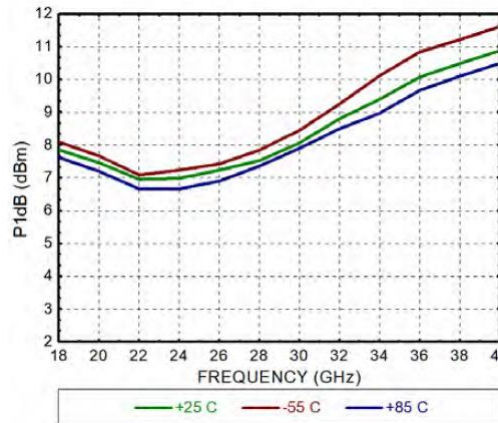


**Gain (VG connected to GND)**

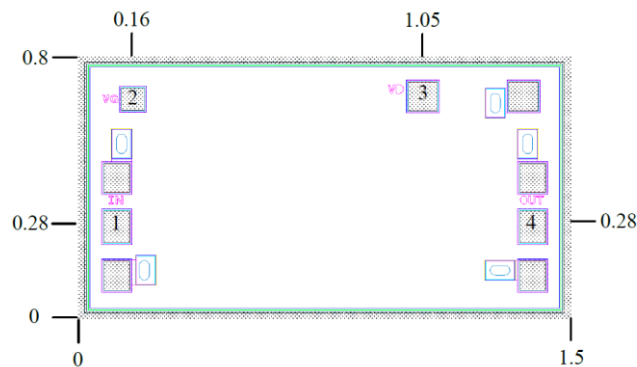


**Return Loss (VG connected to GND)**



**Noise Figure (VG connected to GND)**

**P1dB(VG connected to GND)**

**Outline Drawing:**

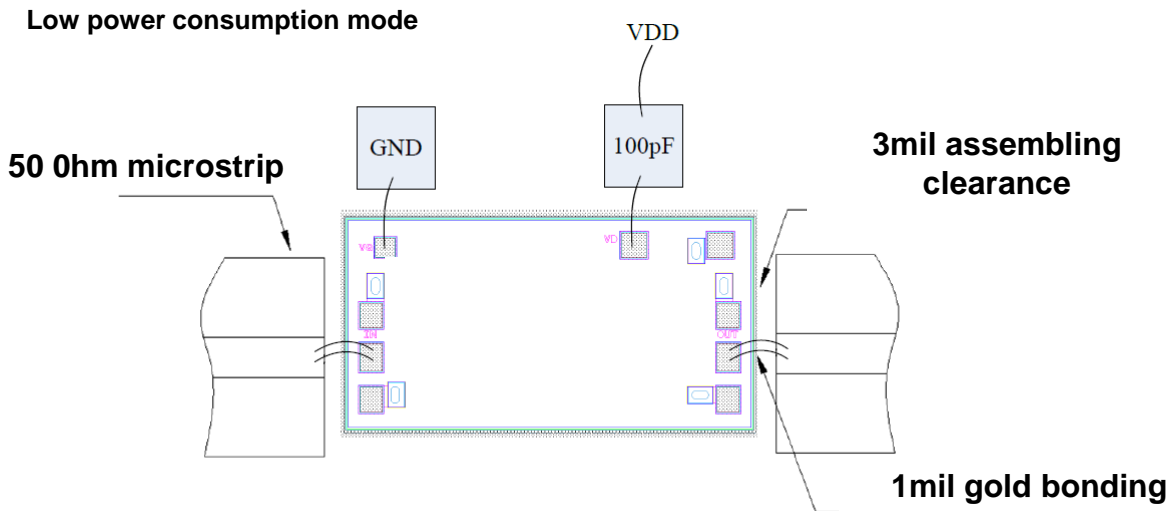
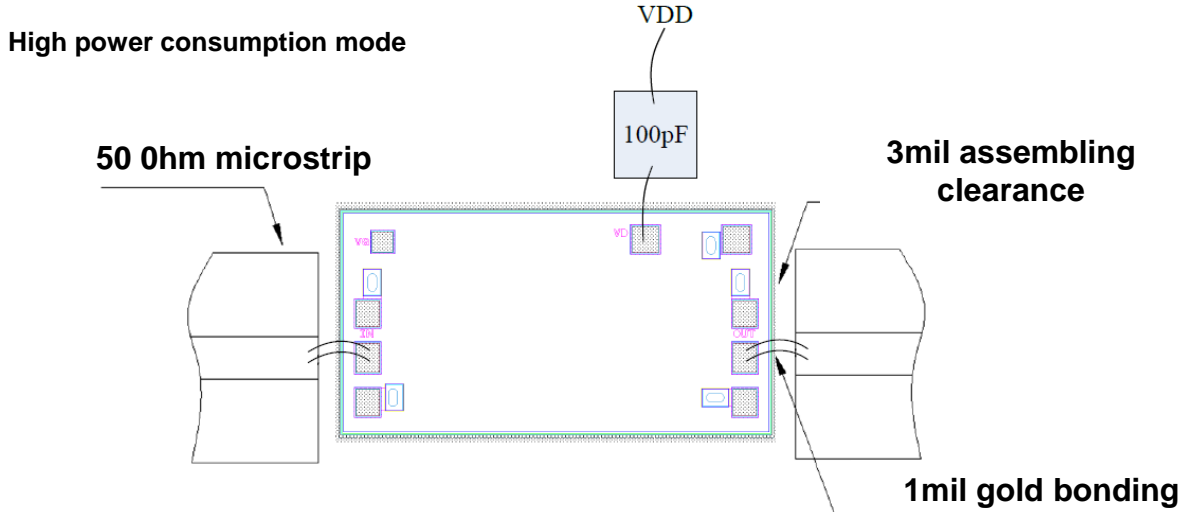
All Dimensions in mm


**Pad Description**

PAD	Function	Description
1	IN	This pad is AC coupling, 50 ohm matched.
2	VG	This pad determines the die's operating mode. When floating, it's high power consumption mode. When connected to RF/DC GND, it's low power consumption mode.
3	VD	This pad provides power supply for the amplifier. It should be connected to extra 100pF bypass capacitor.
4	OUT	This pad is AC coupling, 50 ohm matched.
Die Bottom	GND	Die backside must connect to RF/DC GND.



### Assembly Drawing



#### Notes:

1. Die thickness: 100um
2. Typical bond pad is 100\*80  $\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

#### Maximum Ratings:

1. Maximum drain voltage: +6V
2. Maximum input power: +15dBm
3. Operating temperature: -55°C to +85°C
4. Storage temperature: -65°C to +150°C